

CLAIMS

1. A resin composition, comprising a filler,
a value four times the average particle diameter of
5 the filler being equal to or less than the thickness of the
resin composition, wherein the thickness of the resin
composition is 1000 micrometres (μm) or less and wherein
when the thickness of the resin composition is regarded as
100%, a maximum particle diameter of the filler is 5% to
10 67%.

2. The resin composition according to claim 1, which
is in a sheet form.

15 3. A semiconductor device manufacturing method,
comprising the step of covering a semiconductor chip with
the resin composition recited in claim 1 or 2.

20 4. A semiconductor device, comprising:
a semiconductor chip; and
the resin composition recited in claim 1 or 2 covering
the semiconductor chip.